

## 150V N-Ch Power MOSFET

### Feature

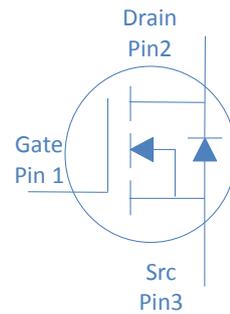
- ◇ High Speed Power Smooth Switching
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free

### Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ Power Tools
- ◇ UPS
- ◇ Motor Control

|                         |         |     |    |
|-------------------------|---------|-----|----|
| $V_{DS}$                |         | 150 | V  |
| $R_{DS(on),typ}$        | TO-220F | 8.8 | mΩ |
| $I_D$ (Silicon Limited) |         | 50  | A  |

TO-220F



| Part Number | Package | Marking   |
|-------------|---------|-----------|
| HGA105N15M  | TO-220F | GA105N15M |

### Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ (unless otherwise specified)

| Parameter                                  | Symbol         | Conditions                             | Value      | Unit             |
|--|----------------|--|------------|------------------|
| Continuous Drain Current (Silicon Limited) | $I_D$          | $T_C=25^\circ\text{C}$                 | 50         | A                |
|  |                | $T_C=100^\circ\text{C}$                | 35         |                  |
| Drain to Source Voltage                    | $V_{DS}$       | -                                      | 150        | V                |
| Gate to Source Voltage                     | $V_{GS}$       | -                                      | $\pm 20$   | V                |
| Pulsed Drain Current                       | $I_{DM}$       | -                                      | 400        | A                |
| Avalanche Energy, Single Pulse             | $E_{AS}$       | $L=0.4\text{mH}, T_C=25^\circ\text{C}$ | 845        | mJ               |
| Power Dissipation                          | $P_D$          | $T_C=25^\circ\text{C}$                 | 333        | W                |
| Operating and Storage Temperature          | $T_J, T_{stg}$ | -                                      | -55 to 175 | $^\circ\text{C}$ |

### Absolute Maximum Ratings

| Parameter                           | Symbol          | Max | Unit               |
|-------------------------------------|-----------------|-----|--------------------|
| Thermal Resistance Junction-Case    | $R_{\theta JC}$ | 2.6 | $^\circ\text{C/W}$ |
| Thermal Resistance Junction-Ambient | $R_{\theta JA}$ | 60  | $^\circ\text{C/W}$ |

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

| Parameter                         | Symbol        | Conditions                                      | Value |     |           | Unit      |
|-----------------------------------|---------------|---|-------|-----|-----------|-----------|
|                                   |               |   | min   | typ | max       |           |
| Drain to Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$                       | 150   | -   | -         | V         |
| Gate Threshold Voltage            | $V_{GS(th)}$  | $V_{GS}=V_{DS}, I_D=250\mu A$                   | 2     | 3   | 4         |           |
| Zero Gate Voltage Drain Current   | $I_{DSS}$     | $V_{GS}=0V, V_{DS}=150V, T_j=25^\circ\text{C}$  | -     | -   | 1         | $\mu A$   |
|                                   |               | $V_{GS}=0V, V_{DS}=150V, T_j=100^\circ\text{C}$ | -     | -   | 100       |           |
| Gate to Source Leakage Current    | $I_{GSS}$     | $V_{GS}=\pm 20V, V_{DS}=0V$                     | -     | -   | $\pm 100$ | nA        |
| Drain to Source on Resistance     | $R_{DS(on)}$  | $V_{GS}=10V, I_D=20A$ TO-220F                   | -     | 8.8 | 10.5      | $m\Omega$ |
| Transconductance                  | $g_{fs}$      | $V_{DS}=5V, I_D=20A$                            | -     | 90  | -         | S         |
| Gate Resistance                   | $R_G$         | $V_{GS}=0V, V_{DS}$ Open, $f=1\text{MHz}$       | -     | 0.7 | -         | $\Omega$  |

**Dynamic Characteristics**

|                               |              |  |   |      |   |         |
|-------------------------------|--------------|--|---|------|---|---------|
| Input Capacitance             | $C_{iss}$    | $V_{GS}=0V, V_{DS}=75V, f=1\text{MHz}$           | - | 4800 | - | $\mu F$ |
| Output Capacitance            | $C_{oss}$    |  | - | 350  | - |         |
| Reverse Transfer Capacitance  | $C_{rss}$    |  | - | 95   | - |         |
| Total Gate Charge             | $Q_g$        | $V_{DD}=75V, I_D=20A, V_{GS}=10V$                | - | 74   | - | nC      |
| Gate to Source Charge         | $Q_{gs}$     |  | - | 15   | - |         |
| Gate to Drain (Miller) Charge | $Q_{gd}$     |  | - | 28   | - |         |
| Turn on Delay Time            | $t_{d(on)}$  | $V_{DD}=75V, I_D=20A, V_{GS}=10V, R_G=10\Omega,$ | - | 20   | - | ns      |
| Rise time                     | $t_r$        |  | - | 58   | - |         |
| Turn off Delay Time           | $t_{d(off)}$ |  | - | 32   | - |         |
| Fall Time                     | $t_f$        |  | - | 31   | - |         |

**Reverse Diode Characteristics**

|                         |          |  |   |     |     |    |
|-------------------------|----------|--|---|-----|-----|----|
| Diode Forward Voltage   | $V_{SD}$ | $V_{GS}=0V, I_F=20A$                   | - | 0.9 | 1.2 | V  |
| Reverse Recovery Time   | $t_{rr}$ | $V_R=75V, I_F=30A, dI_F/dt=100A/\mu s$ | - | 120 | -   | ns |
| Reverse Recovery Charge | $Q_{rr}$ |  | - | 380 | -   | nC |

Fig 1. Typical Output Characteristics

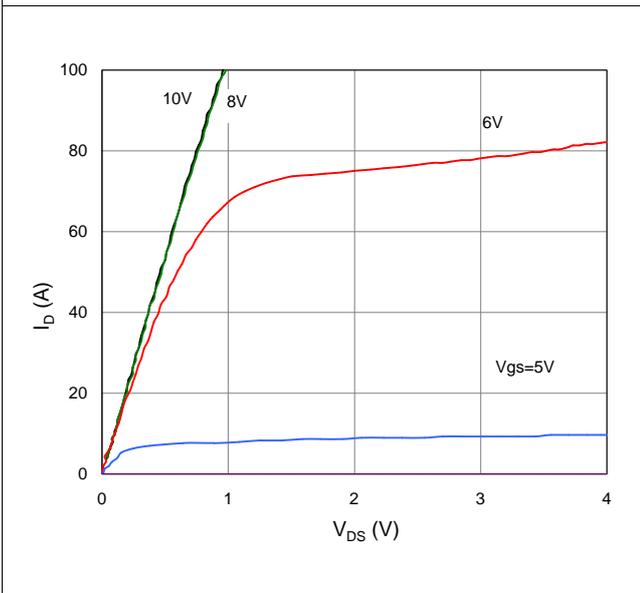


Figure 2. On-Resistance vs. Gate-Source Voltage

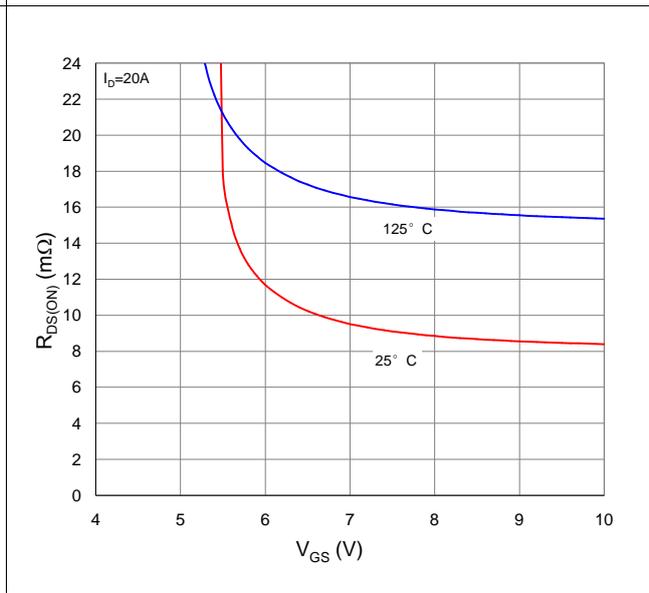


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

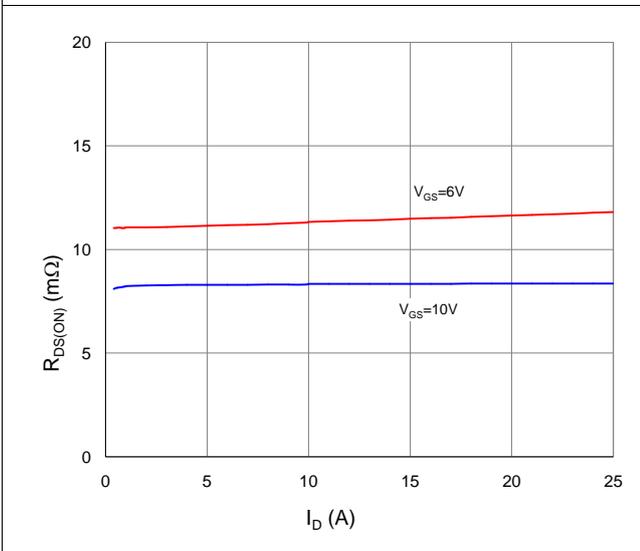


Figure 4. Normalized On-Resistance vs. Junction Temperature

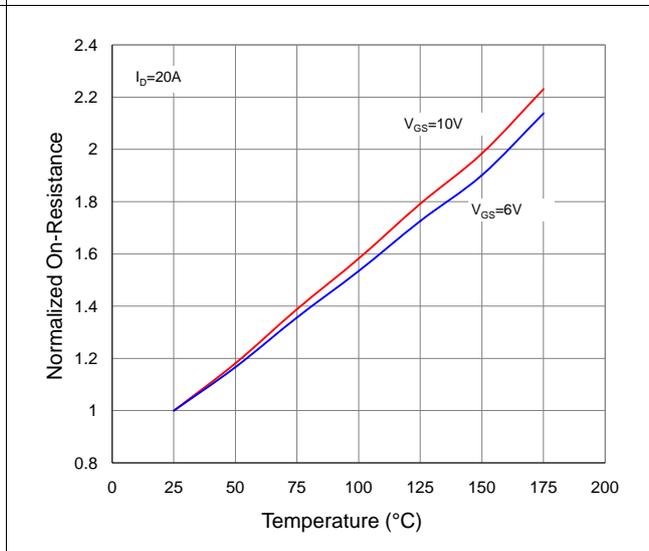


Figure 5. Typical Transfer Characteristics

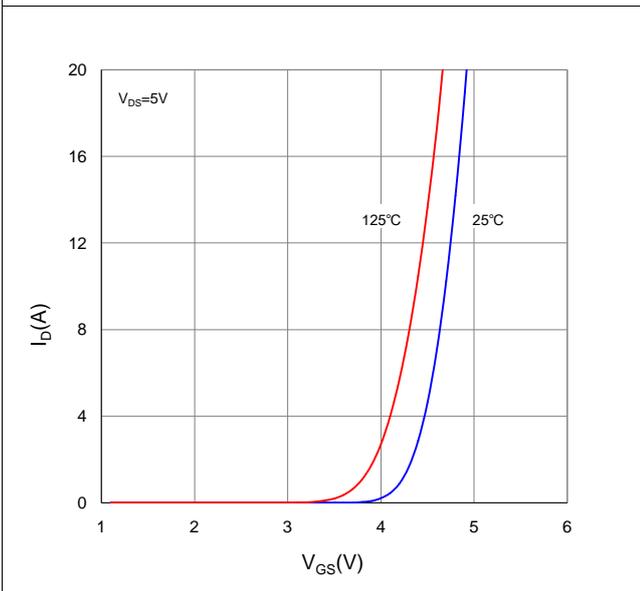


Figure 6. Typical Source-Drain Diode Forward Voltage

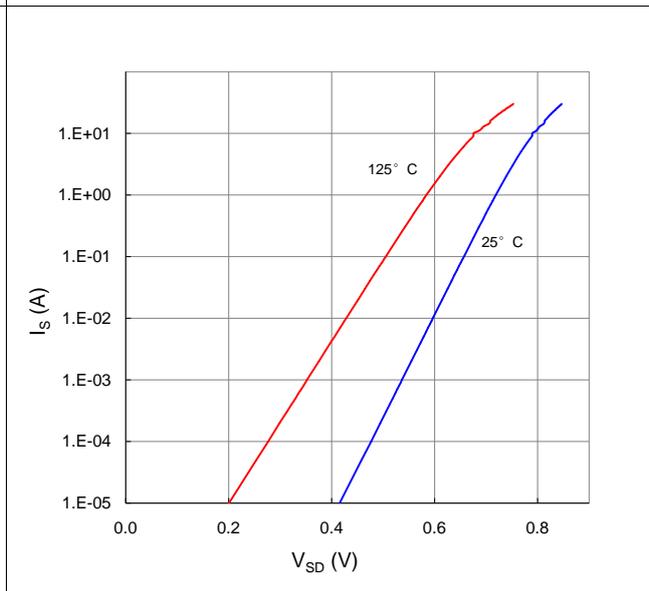


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

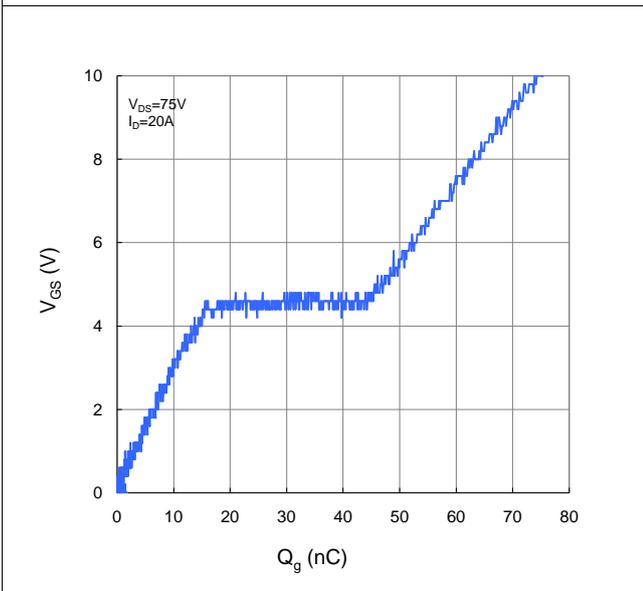


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

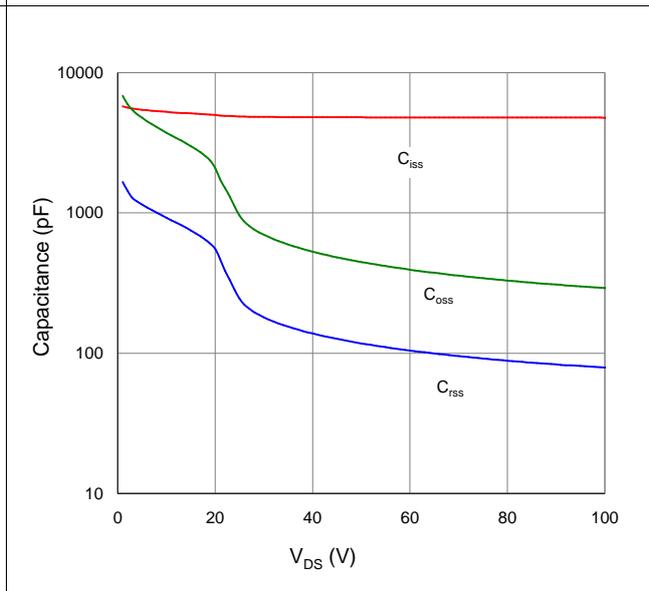


Figure 9. Maximum Safe Operating Area

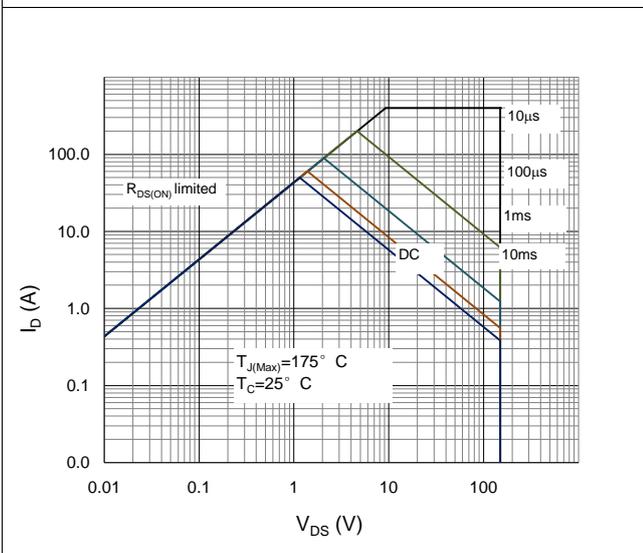


Figure 10. Maximum Drain Current vs. Case Temperature

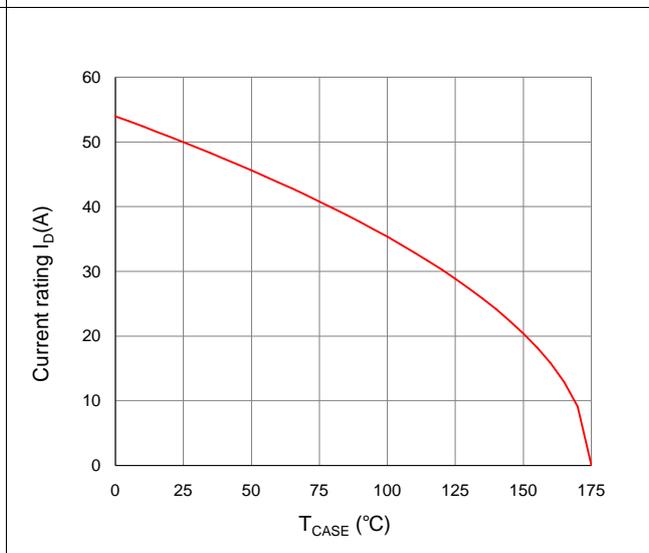
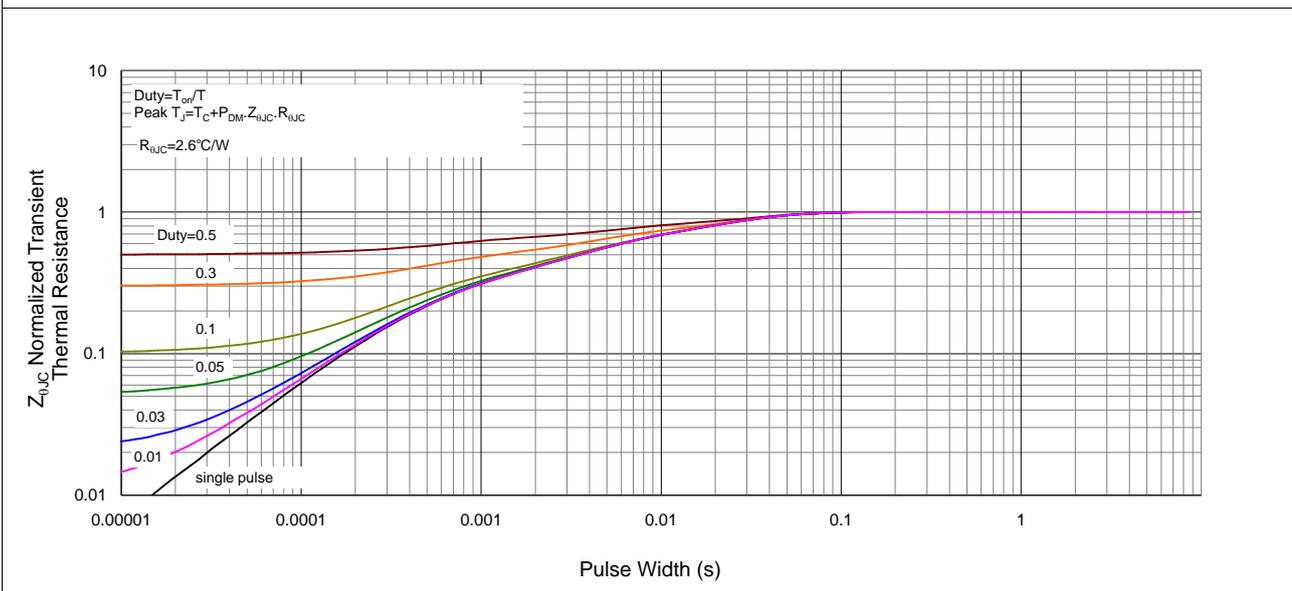
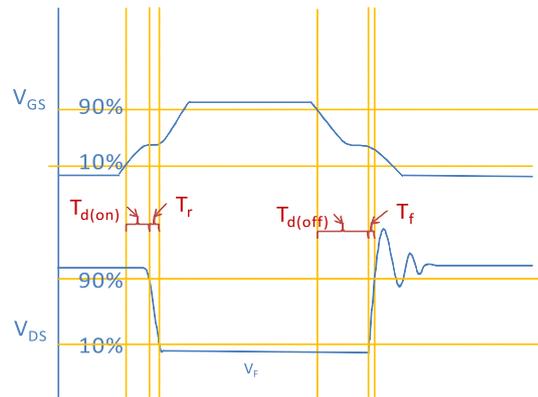
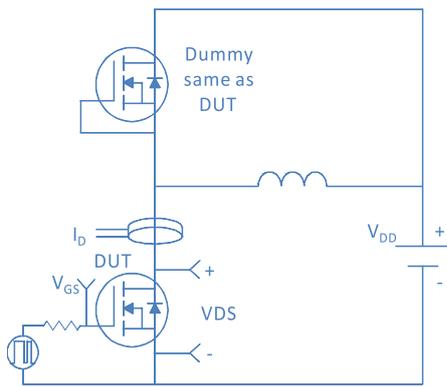


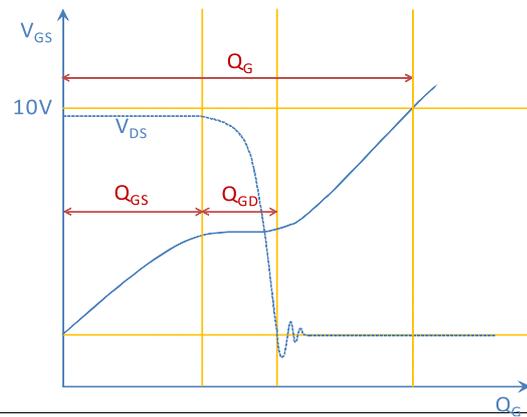
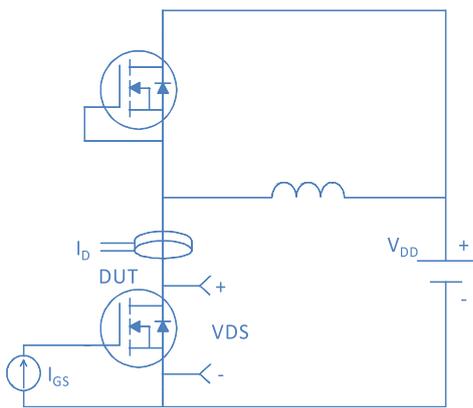
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



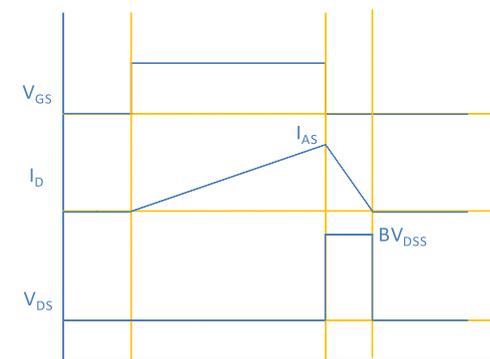
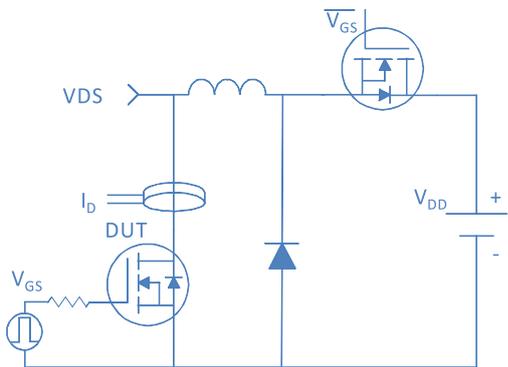
### Inductive switching Test



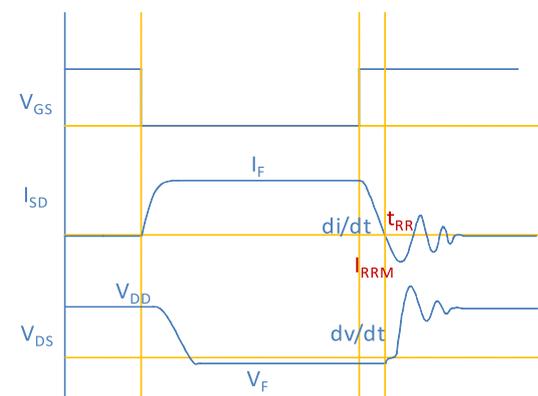
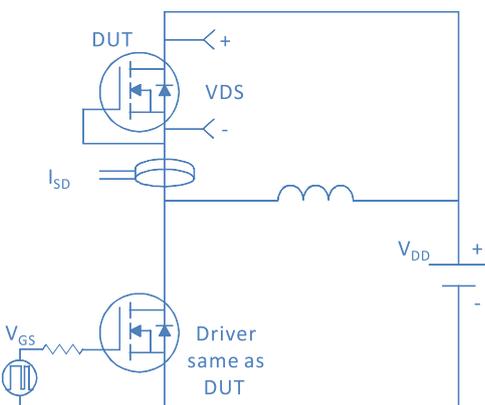
### Gate Charge Test



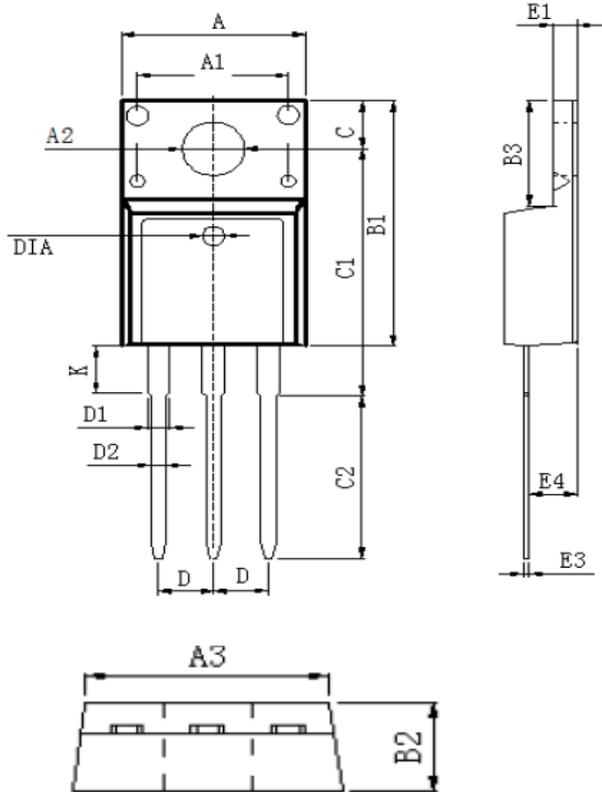
### Uclamped Inductive Switching (UIS) Test



### Diode Recovery Test



## TO-220F, 3 leads



| DIM | MILLIMETERS     |
|-----|-----------------|
| A   | 10.16±0.3       |
| A1  | 7.00±0.1        |
| A2  | 3.3±0.2         |
| A3  | 9.5±0.2         |
| B1  | 15.87±0.3       |
| B2  | 4.7±0.2         |
| B3  | 6.68±0.4        |
| C   | 3.3±0.2         |
| C1  | 12.57±0.3       |
| C2  | 10.02±0.5       |
| D   | 2.54±0.05       |
| D1  | 1.28±0.2        |
| D2  | 0.8±0.1         |
| K   | 3.1±0.3         |
| E1  | 2.54±0.1        |
| E3  | 0.5±0.1         |
| E4  | 2.76±0.2        |
| DIA | ⊙1.5 (deep 0.2) |

Unit :mm